

<1 Ω CMOS, 1.8 V to 5.5 V, Dual SPST Switches

ADG821/ADG822/ADG823

FEATURES

0.8 Ω maximum on resistance @ 125°C
0.3 Ω maximum on resistance flatness @ 125°C
1.8 V to 5.5 V single supply
200 mA current carrying capability
Automotive temperature range: -40°C to +125°C
Rail-to-rail operation
8-lead MSOP

33 ns switching times
Typical power consumption: <0.01 μW
TTL-/CMOS-compatible inputs

Pin-compatible with the ADG721/ADG722/ADG723

APPLICATIONS

Power routing
Battery-powered systems
Communication systems
Data acquisition systems
Audio and video signal routing
Cellular phones
Modems
PCMCIA cards
Hard drives
Relay replacement

GENERAL DESCRIPTION

The ADG821/ADG822/ADG823 are monolithic CMOS single-pole, single-throw (SPST) switches. These switches are designed on an advanced submicron process that provides low power dissipation, yet gives high switching speed, low on resistance, and low leakage currents.

The ADG821/ADG822/ADG823 are designed to operate from a single 1.8 V to 5.5 V supply, making them ideal for use in battery-powered instruments.

Each switch of the ADG821/ADG822/ADG823 conducts equally well in both directions when on. The ADG821/ADG822/ADG823 contain two independent SPST switches. The ADG821 and ADG822 differ only in that both switches are normally open and normally closed, respectively. In the ADG823, Switch 1 is normally open and Switch 2 is normally closed. The ADG823 exhibits break-before-make switching action.

The ADG821/ADG822/ADG823 are available in an 8-lead MSOP.

FUNCTIONAL BLOCK DIAGRAMS

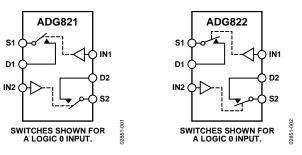


Figure 1.

Figure 2.

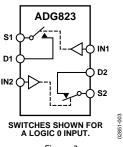


Figure 3.

PRODUCT HIGHLIGHTS

- 1. Very Low On Resistance: 0.5Ω typ.
- 2. On Resistance Flatness ($R_{FLAT(ON)}$): 0.15 Ω typ.
- 3. Automotive Temperature Range: -40°C to +125°C.
- 4. Current Carrying Capability: 200 mA.
- Low Power Dissipation. CMOS construction ensures low power dissipation.
- 6. 8-Lead MSOP.

TABLE OF CONTENTS

Features	1
Applications	
Functional Block Diagrams	
-	
General Description	
Product Highlights	
Revision History	
Specifications	3
Absolute Maximum Ratings	5

ESD Caution	5
Pin Configuration and Function Descriptions	6
Typical Performance Characteristics	7
Test Circuits	9
Terminology	11
Outline Dimensions	12
Ordering Guide	12

REVISION HISTORY

4/08—Rev. 0 to Rev. A

Updated Format	Universal
Added Table 6	6
Updated Outline Dimensions	12
Changes to Ordering Guide	12

8/02—Revision 0: Initial Version

SPECIFICATIONS

 V_{DD} = 5 V \pm 10%, GND = 0 V; T_{A} = -40° C to +125°C, unless otherwise noted.

Table 1.

Parameter	25°C	–40°C to +85°C	−40°C to +125°C¹	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			$0 V to V_{\text{DD}}$	V	
On Resistance (RoN)	0.5			Ω typ	$V_S = 0 \text{ V to } V_{DD}$, $I_S = 100 \text{ mA}$, see Figure 17
	0.6	0.7	0.8	Ω max	
On Resistance Match Between	0.16			Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = 100 \text{ mA}$
Channels (ΔR _{ON})	0.2	0.25	0.28	Ω max	
On Resistance Flatness (RFLAT(ON))	0.15			Ω typ	$V_S = 0 \text{ V to } V_{DD}, I_S = 100 \text{ mA}$
	0.23	0.26	0.3	Ω max	
LEAKAGE CURRENTS					$V_{DD} = 5.5 \text{ V}$
Source Off Leakage, Is (Off)	±0.01			nA typ	$V_S = 4.5 \text{ V/1 V}, V_D = 1 \text{ V/4.5 V}, \text{ see Figure 18}$
	±0.25	±3	±25	nA max	
Drain Off Leakage, I _D (Off)	±0.01			nA typ	$V_S = 4.5 \text{ V/1 V}, V_D = 1 \text{ V/4.5 V}, \text{ see Figure 18}$
	±0.25	±3	±25	nA max	
Channel On Leakage, ID, Is (On)	±0.01			nA typ	$V_S = V_D = 1 \text{ V, or } V_S = V_D = 4.5 \text{ V, see Figure } 19$
	±0.25	±3	±25	nA max	_
DIGITAL INPUTS					
Input High Voltage, VINH			2.0	V min	
Input Low Voltage, V _{INL}			0.8	V max	
Input Current					
I _{INL} or I _{INH}	0.005			μA typ	V _{IN} = V _{INL} or V _{INH}
			±0.1	μA max	
Digital Input Capacitance, C _{IN}	4			pF typ	
DYNAMIC CHARACTERISTICS ²					
ton	33			ns typ	$R_L = 50 \Omega$, $C_L = 35 pF$, $V_S = 3 V$, see Figure 20
	45	48	52	ns max	
toff	11			ns typ	$R_L = 50 \Omega$, $C_L = 35 pF$, $V_S = 3 V$, see Figure 20
	16	19	21	ns max	
Break-Before-Make Time Delay, t _{BBM}	32			ns typ	$R_L = 50 \Omega$, $C_L = 35 pF$, $V_{S1} = V_{S2} = 3 V$,
(ADG823 Only)			1	ns min	see Figure 21
Charge Injection	15			pC typ	$V_S = 2.5 \text{ V}; R_S = 0 \Omega, C_L = 1 \text{ nF, see Figure 22}$
Off Isolation	-52			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$, see Figure 23
Channel-to-Channel Crosstalk	-82			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$, see Figure 24
Bandwidth –3 dB	24			MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$, see Figure 25
C _s (Off)	85			pF typ	f = 1 MHz
C _D (Off)	98			pF typ	f = 1 MHz
C _D , C _s (On)	230			pF typ	f = 1 MHz
POWER REQUIREMENTS				, ,,	$V_{DD} = 5.5 \text{ V}$, digital inputs = 0 V or 5.5 V
I_{DD}	0.001			μA typ	
		1.0	2.0	μA max	

 $^{^{\}scriptscriptstyle 1}$ On resistance parameters tested with $I_{\scriptscriptstyle S}$ = 10 mA.

² Guaranteed by design, not subject to production test.

 V_{DD} = 2.7 V to 3.6 V, GND = 0 V, T_A = -40°C to +125°C, unless otherwise noted.

Table 2.

Parameter	25°C	−40°C to +85°C	-40°C to +125°C ¹	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			$0VtoV_{DD}$	V	
On Resistance (RoN)	0.7			Ωtyp	$V_S = 0 \text{ V to } V_{DD}$, $I_S = 100 \text{ mA}$, see Figure 17
	1.4	1.5	1.6	Ω max	
On Resistance Match Between	0.16			Ωtyp	$V_S = 0 \text{ V to } V_{DD}$, $I_S = 100 \text{ mA}$
Channels (ΔR _{ON})	0.2	0.25	0.28	Ω max	
On Resistance Flatness (RFLAT(ON))	0.3		0.33	Ωtyp	$V_S = 0 \text{ V to } V_{DD}$, $I_S = 100 \text{ mA}$
LEAKAGE CURRENTS					$V_{DD} = 3.6 \text{ V}$
Source Off Leakage, I _s (Off)	±0.01			nA typ	$V_S = 3.3 \text{ V/1 V}, V_D = 1 \text{ V/3.3 V}, \text{ see Figure 18}$
	±0.25	±3	±15	nA max	
Drain Off Leakage, I _D (Off)	±0.01			nA typ	$V_S = 3.3 \text{ V/1 V}, V_D = 1 \text{ V/3.3 V}, \text{ see Figure 18}$
-	±0.25	±3	±25	nA max	
Channel On Leakage, ID, IS (On)	±0.01			nA typ	$V_S = V_D = 1 \text{ V, or } 3.3 \text{ V, see Figure } 19$
-	±0.25	±3	±25	nA max	
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2.0	V min	
Input Low Voltage, V _{INL}			0.8	V max	
Input Current					
I _{INL} or I _{INH}	0.005			μA typ	$V_{IN} = V_{INL}$ or V_{INH}
			±0.1	μA max	
Digital Input Capacitance, C _{IN}	4			pF typ	
DYNAMIC CHARACTERISTICS ²					
ton	48			ns typ	$R_L = 50 \Omega$, $C_L = 35 pF$, $V_S = 1.5 V$, see Figure 20
	67	74	78	ns max	
toff	12			ns typ	$R_L = 50 \Omega$, $C_L = 35 pF$, $V_S = 1.5 V$, see Figure 20
	18	20	23	ns max	
Break-Before-Make Time Delay, tbbM	40			ns typ	$R_L = 50 \Omega$, $C_L = 35 pF$, $V_{S1} = V_{S2} = 1.5 V$,
(ADG823 Only)			1	ns min	see Figure 21
Charge Injection	±2			pC typ	$V_S = 1.5 \text{ V}; R_S = 0 \Omega, C_L = 1 \text{ nF, see Figure 22}$
Off Isolation	-52			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$, see Figure 23
Channel-to-Channel Crosstalk	-82			dB typ	$R_L = 50 \Omega$, $C_L = 5 pF$, $f = 1 MHz$, see Figure 24
Bandwidth –3 dB	24			MHz typ	$R_L = 50 \Omega$, $C_L = 5 pF$, see Figure 25
C _s (Off)	85			pF typ	f = 1 MHz
C _D (Off)	98			pF typ	f = 1 MHz
C_D , C_S (On)	230			pF typ	f = 1 MHz
POWER REQUIREMENTS				†	$V_{DD} = 3.6 \text{ V}$, digital inputs = 0 V or 3.6 V
I _{DD}	0.001			μA typ	
		1.0	2.0	μA max	

 $^{^{1}}$ On resistance parameters tested with l_{S} = 10 mA. 2 Guaranteed by design, not subject to production test.

ABSOLUTE MAXIMUM RATINGS

 $T_A = 25$ °C, unless otherwise noted.

Table 3.

Table 3.	
Parameter	Rating
V _{DD} to GND	−0.3 V to +7 V
Analog Inputs ¹	$-0.3 \text{ V to V}_{DD} + 0.3 \text{ V or } 30 \text{ mA},$ whichever occurs first
Digital Inputs ¹	$-0.3 \text{ V to V}_{DD} + 0.3 \text{ V or } 30 \text{ mA},$ whichever occurs first
Peak Current, S or D	400 mA (pulsed at 1 ms, 10% duty cycle maximum)
Continuous Current, S or D	200 mA
Operating Temperature Range	
Automotive	−40°C to +125°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature (T _J max)	150°C
Package Power Dissipation	$(T_J \max - T_A)/\theta_{JA}$
8-Lead MSOP Thermal Impedance	
Θ_{JA}	206°C/W
$oldsymbol{ heta}$ JC	44°C/W
Lead Temperature, Soldering (10 sec)	300°C
IR Reflow, Peak Temperature (<20 sec)	235℃

¹ Overvoltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 4. Truth Table for the ADG821/ADG822

ADG821 INx	ADG822 INx	Switch x Condition
0	1	Off
1	0	On

Table 5. Truth Table for the ADG823

IN1	IN2	Switch S1	Switch S2
0	0	Off	On
0	1	Off	Off
1	0	On	On
1	1	On	Off

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

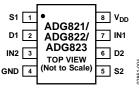


Figure 4. Pin Configuration

Table 6. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	S1	Source Terminal. This pin can be an input or output.
2	D1	Drain Terminal. This pin can be an input or output.
3	IN2	Logic Control Input.
4	GND	Ground (0 V) Reference.
5	S2	Source Terminal. This pin can be an input or output.
6	D2	Drain Terminal. This pin can be an input or output.
7	IN1	Logic Control Input.
8	V_{DD}	Most Positive Power Supply Potential.

TYPICAL PERFORMANCE CHARACTERISTICS

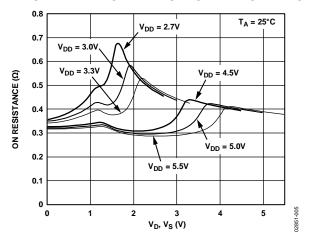


Figure 5. On Resistance vs. V_D , V_S

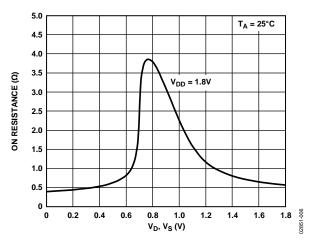


Figure 6. On Resistance vs. V_D , V_S ; $V_{DD} = 1.8 \text{ V}$

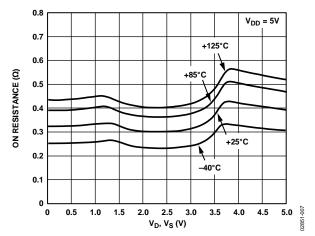


Figure 7. On Resistance vs. V_D , V_S for Different Temperatures, $V_{DD} = 5 V$

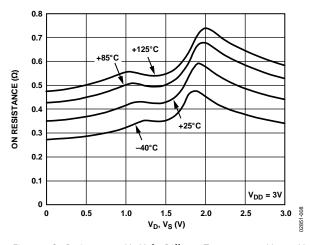


Figure 8. On Resistance vs. V_D , V_S for Different Temperatures, $V_{DD} = 3 \text{ V}$

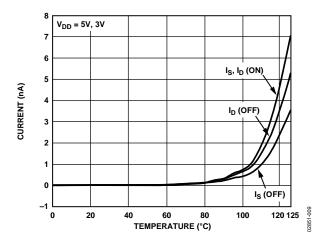


Figure 9. Leakage Current vs. Temperature

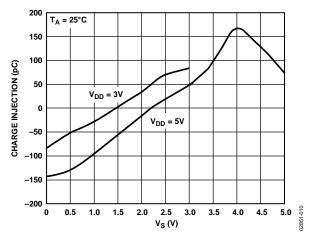


Figure 10. Charge Injection vs. Source Voltage

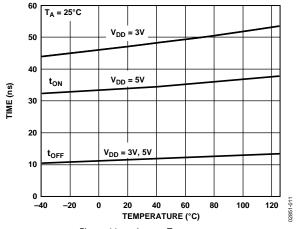


Figure 11. t_{ON}/t_{OFF} vs. Temperature

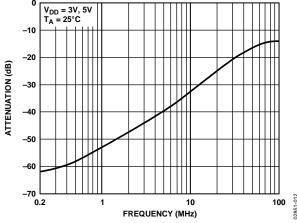


Figure 12. Off Isolation vs. Frequency

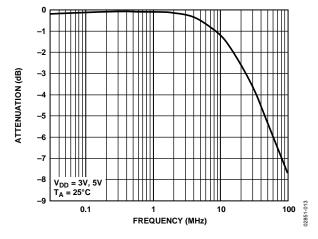


Figure 13. On Response vs. Frequency

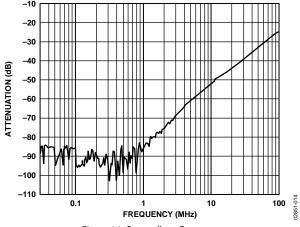


Figure 14. Crosstalk vs. Frequency

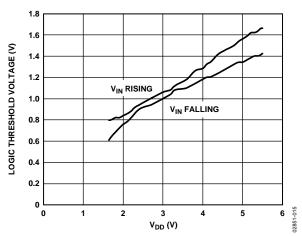


Figure 15. Logic Threshold Voltage vs. Supply Voltage

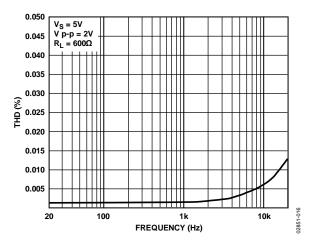
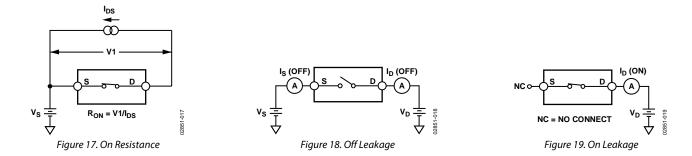


Figure 16. THD vs. Frequency

TEST CIRCUITS



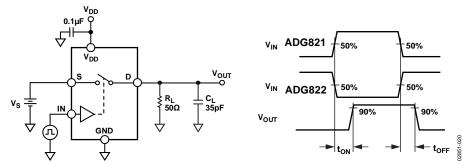


Figure 20. Switching Times

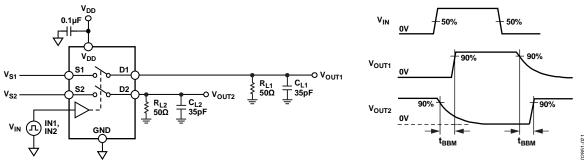


Figure 21. Break-Before-Make Time Delay, t_{BBM} (ADG823 only)

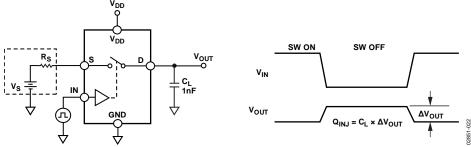


Figure 22. Charge Injection

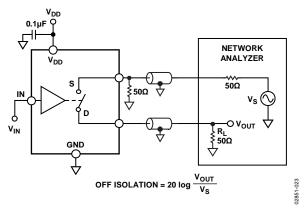


Figure 23. Off Isolation

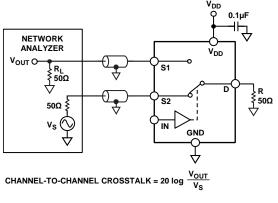


Figure 24. Channel-to-Channel Crosstalk

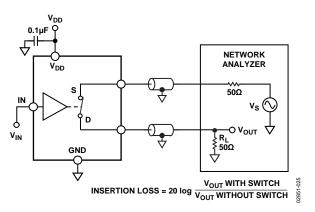


Figure 25. Bandwidth

TERMINOLOGY

 \mathbf{V}_{DD}

Most positive power supply potential.

GND

Ground (0 V) reference.

 \mathbf{I}_{DD}

Positive supply current.

S

Source terminal. May be an input or output.

D

Drain terminal. May be an input or output.

IN

Logic control input.

Ron

Ohmic resistance between Terminal D and Terminal S.

 ΔR_{ON}

On resistance match between any two channels (that is,

 R_{ON} max – R_{ON} min).

 $R_{\text{FLAT(ON)}}$

Flatness is defined as the difference between the maximum and minimum value of on resistance as measured over the specified analog signal range.

Is (Off)

Source leakage current with the switch off.

I_D (Off)

Drain leakage current with the switch off.

ID, Is (On)

Channel leakage current with the switch on.

 V_D , V_S

Analog voltage on Terminal D and Terminal S.

 \mathbf{V}_{INL}

Maximum input voltage for Logic 0.

 V_{INH}

Minimum input voltage for Logic 1.

 $I_{INL}(I_{INH})$

Input current of the digital input.

Cs (Off)

Off switch source capacitance.

C_D (Off)

Off switch drain capacitance.

 $C_D, C_S(On)$

On switch capacitance.

ton

Delay between applying the digital control input and the output switching on.

 t_{OFF}

Delay between applying the digital control input and the output switching off.

 t_{BBM}

Off time or on time measured between the 90% points of both switches, when switching from one address state to another.

Charge Injection

Charge injection is a measure of the glitch impulse transferred from the digital input to the analog output during switching.

Crosstalk

Crosstalk is a measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

Off Isolation

A measure of unwanted signal coupling through an off switch.

Bandwidth

The frequency at which the output is attenuated by -3 dBs.

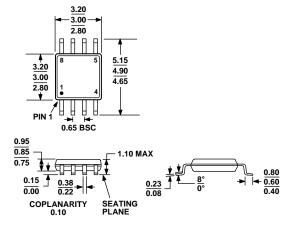
On Response

The frequency response of the on switch.

Insertion Loss

The loss due to the on resistance of the switch.

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-187-AA

Figure 26. 8-Lead Mini Small Outline Package [MSOP] (RM-8) Dimensions shown in millimeters

ORDERING GUIDE

Model	Temperature Range	Package Description	Package Option	Branding
ADG821BRM	-40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SQB
ADG821BRM-REEL	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SQB
ADG821BRMZ ¹	-40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	S0P
ADG821BRMZ-REEL7 ¹	-40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SOP
ADG822BRM	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SRB
ADG822BRM-REEL	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SRB
ADG822BRM-REEL7	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SRB
ADG822BRMZ ¹	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	S1J
ADG822BRMZ-REEL7 ¹	-40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	S1J
ADG823BRM	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SSB
ADG823BRM-REEL	−40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SSB
ADG823BRMZ ¹	-40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SSB#
ADG823BRMZ-REEL7 ¹	-40°C to +125°C	8-Lead Mini Small Outline Package [MSOP]	RM-8	SSB#

 $^{^{1}}$ Z = RoHS Compliant Part, # denotes RoHS compliant product may be top or bottom marked.



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Analogue Switch ICs category:

Click to view products by Analog Devices manufacturer:

Other Similar products are found below:

FSA3051TMX NLAS4684FCTCG NLAS5223BLMNR2G NLVAS4599DTT1G NLX2G66DMUTCG 425541DB 425528R 099044FB
NLAS5123MNR2G PI5A4157CEX PI5A4599BCEX NLAS4717EPFCT1G PI5A3167CCEX SLAS3158MNR2G PI5A392AQE
PI5A4157ZUEX PI5A3166TAEX FSA634UCX TC4066BP(N,F) DG302BDJ-E3 PI5A100QEX HV2605FG-G HV2301FG-G
RS2117YUTQK10 RS2118YUTQK10 RS2227XUTQK10 ADG452BRZ-REEL7 MAX4066ESD+ MAX391CPE+ MAX4730EXT+T
MAX314CPE+ BU4066BCFV-E2 MAX313CPE+ BU4S66G2-TR NLAS3158MNR2G NLASB3157MTR2G TS3A4751PWR
NLAS4157DFT2G NLAS4599DFT2G NLASB3157DFT2G NLAST4599DFT2G NLAST4599DTT1G DG300BDJ-E3 DG2503DB-T2-GE1
DG2502DB-T2-GE1 TC4W53FU(TE12L,F) 74HC2G66DC.125 ADG619BRMZ-REEL ADG1611BRUZ-REEL7 LTC201ACN#PBF